Chia-Chi Tuan

List of Publications by Year
in descending order

28 papers	1,064 citations	687363 13 h-index	752698 20 g-index
28 all docs	28 docs citations	28 times ranked	1822 citing authors

#	Article	IF	Citations
1	Uniform Metal-Assisted Chemical Etching for Ultra-High-Aspect-Ratio Microstructures on Silicon. Journal of Microelectromechanical Systems, 2019, 28, 143-153.	2.5	18
2	High-aspect-ratio microstructures with versatile slanting angles on silicon by uniform metal-assisted chemical etching. Journal of Micromechanics and Microengineering, 2018, 28, 055006.	2.6	5
3	Controlled synthesis and evaluation of cyanate ester/epoxy copolymer system for high temperature molding compounds. Journal of Polymer Science Part A, 2018, 56, 1337-1345.	2.3	19
4	Polyimide incorporated cyanate ester/epoxy copolymers for highâ€temperature molding compounds. Journal of Polymer Science Part A, 2018, 56, 2412-2421.	2.3	11
5	A high-performance TiO2 nanotube supercapacitor by tuning heating rate during H2 thermal annealing. Journal of Materials Science: Materials in Electronics, 2018, 29, 15130-15137.	2.2	3
6	Controlling Kink Geometry in Nanowires Fabricated by Alternating Metal-Assisted Chemical Etching. Nano Letters, 2017, 17, 1014-1019.	9.1	50
7	Ultrafast Molecular Stitching of Graphene Films at the Ethanol/Water Interface for High Volumetric Capacitance. Nano Letters, 2017, 17, 1365-1370.	9.1	42
8	Self-Patterning of Silica/Epoxy Nanocomposite Underfill by Tailored Hydrophilic-Superhydrophobic Surfaces for 3D Integrated Circuit (IC) Stacking. ACS Applied Materials & Interfaces, 2017, 9, 8437-8442.	8.0	13
9	Fabricating and Controlling Silicon Zigzag Nanowires by Diffusion-Controlled Metal-Assisted Chemical Etching Method. Nano Letters, 2017, 17, 4304-4310.	9.1	48
10	Effects of Defects on the Mechanical Properties of Kinked Silicon Nanowires. Nanoscale Research Letters, 2017, 12, 185.	5.7	11
11	Epoxy/Cyanate Ester Copolymer Material for Molding Compounds in High-Temperature Operations. , 2017, , .		12
12	Toughening Underfills by Stress-Absorbing Core-Shell Fillers. , 2017, , .		0
13	A novel, facile, layer-by-layer substrate surface modification for the fabrication of all-inkjet-printed flexible electronic devices on Kapton. Journal of Materials Chemistry C, 2016, 4, 7052-7060.	5.5	23
14	Polysiloxane-Based Surface Modification of Silica Fillers for Low Stress Underfill. , 2016, , .		2
15	1D Niâ€“Co oxide and sulfide nanoarray/carbon aerogel hybrid nanostructures for asymmetric supercapacitors with high energy density and excellent cycling stability. Nanoscale, 2016, 8, 16292-16301.	5.6	101
16	A Novel Approach to Integrating 3D/4D Printing and Stretchable Conductive Adhesive Technologies for High Frequency Packaging Applications. , 2016, , .		0
17	Vertically Aligned and Interconnected Graphene Networks for High Thermal Conductivity of Epoxy Composites with Ultralow Loading. Chemistry of Materials, 2016, 28, 6096-6104.	6.7	325
18	A facile and low-cost route to high-aspect-ratio microstructures on silicon via a judicious combination of flow-enabled self-assembly and metal-assisted chemical etching. Journal of Materials Chemistry C, 2016, 4, 8953-8961.	5.5	9

#	Article	IF	Citations
19	Highly Conductive Polyurethane/Polyaniline-Based Composites for Wearable Electronic Applications. , 2016, , .		7
20	Molecular Level Study of Graphene Networks Functionalized with Phenylenediamine Monomers for Supercapacitor Electrodes. Chemistry of Materials, 2016, 28, 9110-9121.	6.7	98
21	Formation of Polymer Insulation Layer (Liner) on Through Silicon Vias (TSV) with High Aspect Ratio over 5:1 by Direct Spin Coating. , 2016, , .		6
22	Molecular engineering of aromatic amine spacers for high-performance graphene-based supercapacitors. Nano Energy, 2016, 21, 276-294.	16.0	61
23	The hybrid nanostructure of MnCo₂O_{4.5} nanoneedle/carbon aerogel for symmetric supercapacitors with high energy density. Nanoscale, 2015, 7, 14401-14412.	5.6	99
24	Capacitance enhancement by electrochemically active benzene derivatives for graphene-based supercapacitors. RSC Advances, 2015, 5, 84113-84118.	3.6	8
25	Self-patterning, pre-applied underfilling technology for stack-die packaging. , 2014, , .		1
26	High Refractive Index and Transparent Nanocomposites as Encapsulant for High Brightness LED Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1125-1130.	2.5	17
27	Ultra-high refractive index LED encapsulant. , 2014, , .		5
28	Ligand-Controlled Colloidal Synthesis and Electronic Structure Characterization of Cubic Iron Pyrite (FeS₂) Nanocrystals. Chemistry of Materials, 2013, 25, 1615-1620.	6.7	70